

IN THE SPECIFICATION

On the application cover page, please amend as follows:

UNITED STATES PATENT APPLICATION

for

A Bonded Wafer Processing Method

Inventors:

Patrick Morrow
R. Scott List
Michael Y. Chan

Prepared by:

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP
12400 Wilshire Boulevard
Los Angeles, CA 90025-1026
(303) 740-1980

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Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP



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Mark L. Watson
Reg. No. 46,322

12400 Wilshire Boulevard
7th Floor
Los Angeles, California 90025-1026
(303) 740-1980